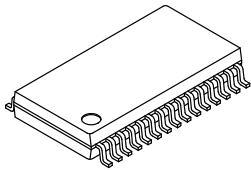


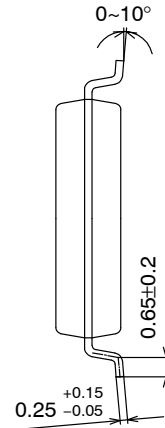
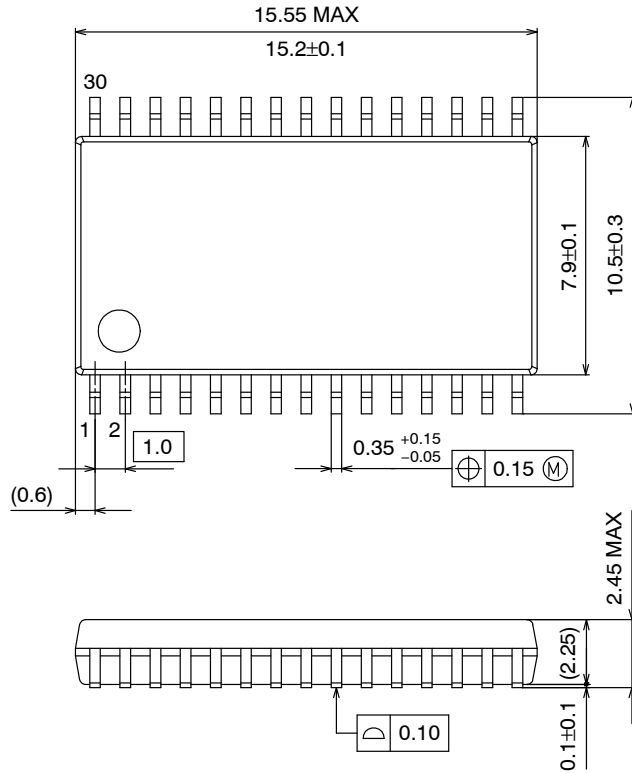
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

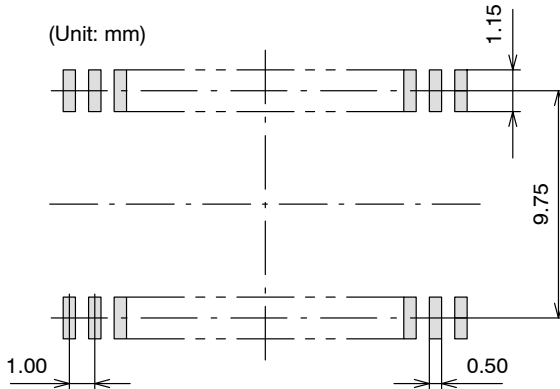


MFP30SDJ (375 mil)
CASE 751CP
ISSUE A

DATE 08 NOV 2013



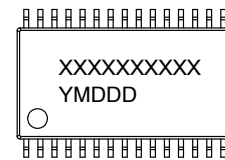
SOLDERING FOOTPRINT*



NOTE: The measurements are not to guarantee but for reference only.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
 Y = Year
 M = Month
 DDD = Additional Traceability Data

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	MFP30SDJ (375 MIL)	PAGE 1 OF 2

